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Sheet 1 of 1

Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DKT. NO. 501.36127CC2	SERIAL NO. <b>10/619039</b>
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (Use several sheets if necessary)		APPLICANT KOUBUCHI, et al.	
		FILING DATE July 10, 2003	GROUP 2825

**U.S. PATENT DOCUMENTS**

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
CP	AA 5,929,528	7-27-99	Kinugawa	257	776	
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	AC 5,892,277	4-6-99	Ikemizu, et al.	257	700	
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**FOREIGN PATENT DOCUMENTS**

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation / Abstract	
						Yes	No
CP	AM 7-74175	3-17-95	Japan			X	
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CP	AO 8314762	26-11-96	Japan			Corresponding USP '139	
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CP	AU	Lee, et al., "An Optimized Densification of the Filled Oxide for Quarter Micron Shallow Trench Isolation (STI)", 1996, Symposium on VLSI Technology Digest of Technical Papers, pp. 158-159.
	AV	
	AW	
	AX	
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	AZ	

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